## 2SD970(K)

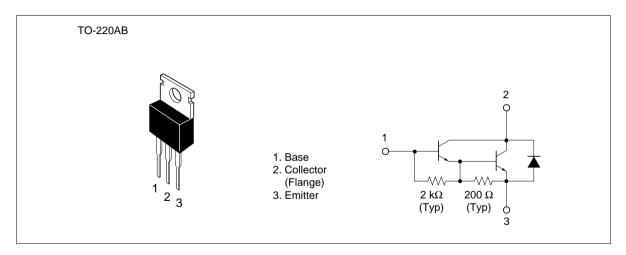
### Silicon NPN Triple Diffused

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#### Application

Medium speed and power switching complementary pair with 2SB791(K)

#### Outline



#### **Absolute Maximum Ratings** (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V <sub>CBO</sub>	120	V
Collector to emitter voltage	V <sub>CEO</sub> 120		V
Emitter to base voltage	V <sub>EBO</sub>	7	V
Collector current	Ι <sub>c</sub>	8	А
Collector peak current	I <sub>C(peak)</sub>	12	А
Collector power dissipation	P <sub>c</sub> * <sup>1</sup>	40	W
Junction temperature	Тј	150	°C
Storage temperature	Tstg	-55 to +150	°C
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Note: 1. Value at  $T_c = 25^{\circ}C$ .

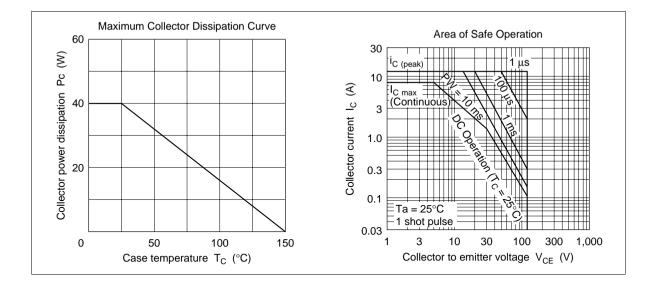


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#### **Electrical Characteristics** (Ta = 25°C)

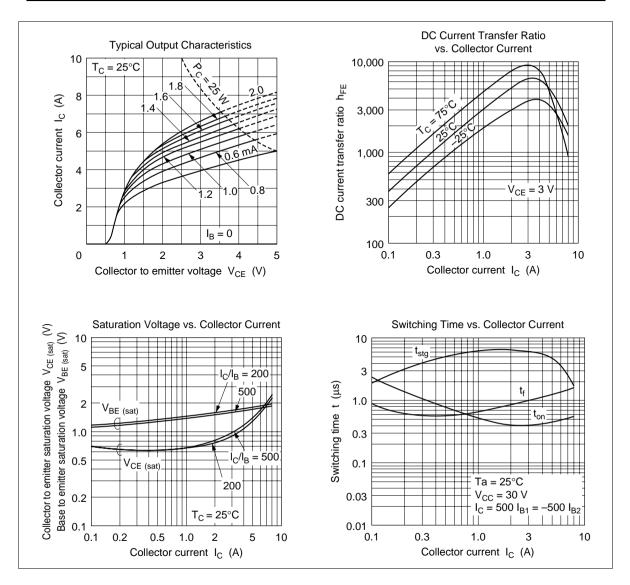
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	120	-	_	V	$I_c = 25 \text{ mA}, \text{ R}_{\text{BE}} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	7	_	_	V	$I_{\rm E} = 50$ mA, $I_{\rm C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_		100	μA	$V_{CB} = 120 \text{ V}, I_{E} = 0$
	I <sub>CEO</sub>	—		10	μΑ	$V_{ce}$ = 100 V, $R_{be}$ = $\infty$
DC current transfer ratio	$h_{\text{FE}}$	1000		20000		$V_{ce} = 3 \text{ V}, \text{ I}_{c} = 4 \text{ A}^{*1}$
Collector to emitter saturation	$V_{\text{CE(sat)1}}$	—	—	1.5	V	$I_{\rm c} = 4 \text{ A}, I_{\rm B} = 8 \text{ mA}^{*1}$
voltage	$V_{\text{CE(sat)2}}$	—	_	3.0	V	$I_{\rm c} = 8 \text{ A}, I_{\rm B} = 80 \text{ mA}^{*1}$
Base to emitter saturation	$V_{BE(sat)1}$	—		2.0	V	$I_{\rm c} = 4 \text{ A}, I_{\rm B} = 8 \text{ mA}^{*1}$
voltage	$V_{BE(sat)^2}$	—	—	3.5	V	$I_{\rm c} = 8 \text{ A}, I_{\rm B} = 80 \text{ mA}^{*1}$
Turn on time	t <sub>on</sub>	—	0.4	_	μs	$I_{\rm C} = 4$ A, $I_{\rm B1} = -I_{\rm B2} = 8$ mA
Storage time	t <sub>stg</sub>	_	5.4		μs	
Fall time	t <sub>f</sub>	_	1.1	_	μs	

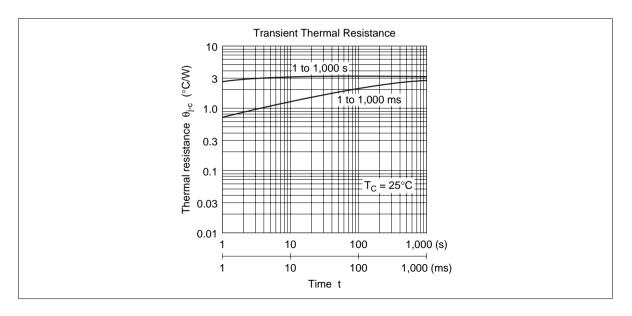
Note: 1. Pulse test.



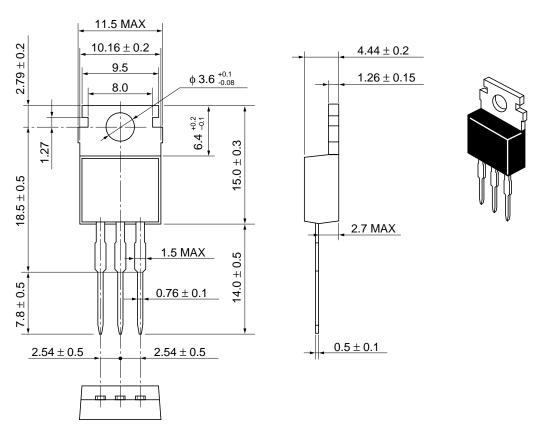
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Hitachi Code	TO-220AB
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.8 g

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